

DLBeam™ High Speed Connectors

Engineered for Enhanced Signal Integrity

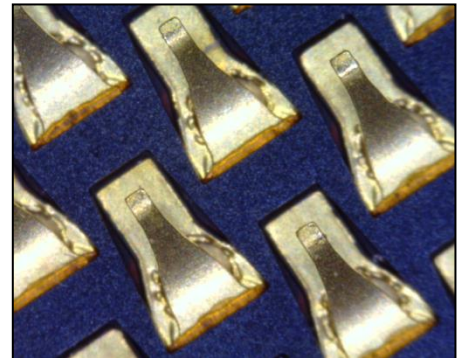
OVERVIEW

Engineered specifically for high speed, the DLBeam™ construction offers enhanced signal integrity for applications up to 56Gbps. Utilizing a modified design and manufacturing flow, DLBeam products take advantage of 60% less surface area to significantly reduce parasitic capacitance. The design also features a shorter, more direct signal path to minimize attenuation.

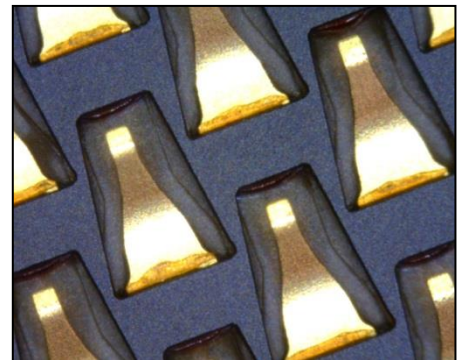
The new DLBeam interposer construction is offered at 1mm pitch or greater. DLBeam products are offered in thicknesses from 0.75mm – 3.5mm and with LGA/LGA or LGA/BGA configuration. Coreless DLBeam option has a standard thickness of 0.45mm, with capability to 0.30mm, and is offered in LGA/LGA configuration.

FEATURES

- Now available for PCBeam™ designs at 1mm pitch or greater
- Up to 70% less insertion loss vs. standard PCBeam at 20GHz
- Ultra-low profile capability as low as 0.30mm (coreless option)
- Thickness up to 3.5mm
- Current capacity to >2A per single position
- Separable (LGA/LGA) or solderable (LGA/BGA) mounting options
- Mechanically interchangeable with standard PCBeam interposers (no hardware changes needed if migrating to DLBeam)
- Compliant with ROHS 2011/65/EU and IPC-4101B (halogen-free)



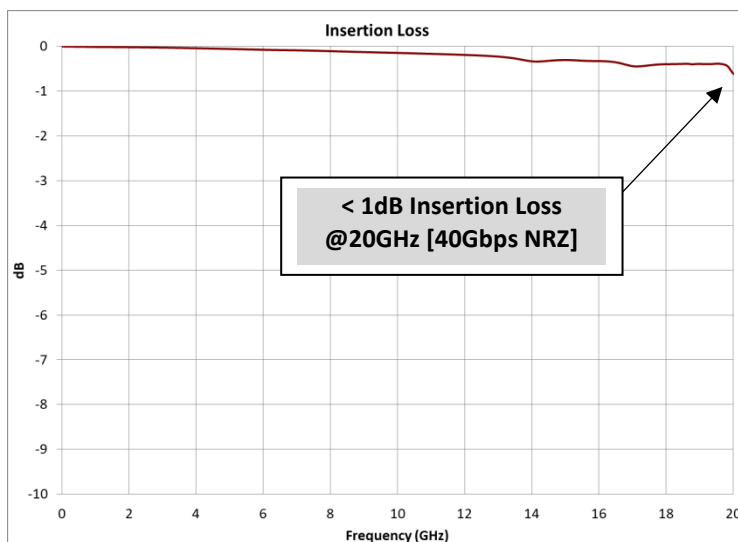
PCBeam™ Standard Construction



DLBeam™ Construction



Ultra-Thin Coreless DLBeam



FOR MORE INFORMATION

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